
ZXMS6005SG
60V N-CHANNEL SELF PROTECTED ENHANCEMENT MODE
INTELLIFET™ MOSFET

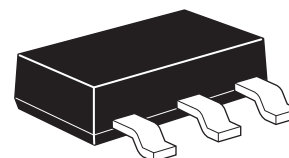
SUMMARY

Continuous drain source voltage 60 V

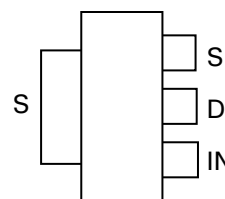
On-state resistance 200 mΩ

Nominal load current ($V_{IN} = 5V$) 2 A

Clamping Energy 480 mJ


SOT223 Package
DESCRIPTION

The ZXMS6005SG is a self protected low side MOSFET with logic level input. It integrates over-temperature, over-current, over-voltage (active clamp) and ESD protected logic level functionality. The ZXMS6005SG is ideal as a general purpose switch driven from 3.3V or 5V microcontrollers in harsh environments where standard MOSFETs are not rugged enough.

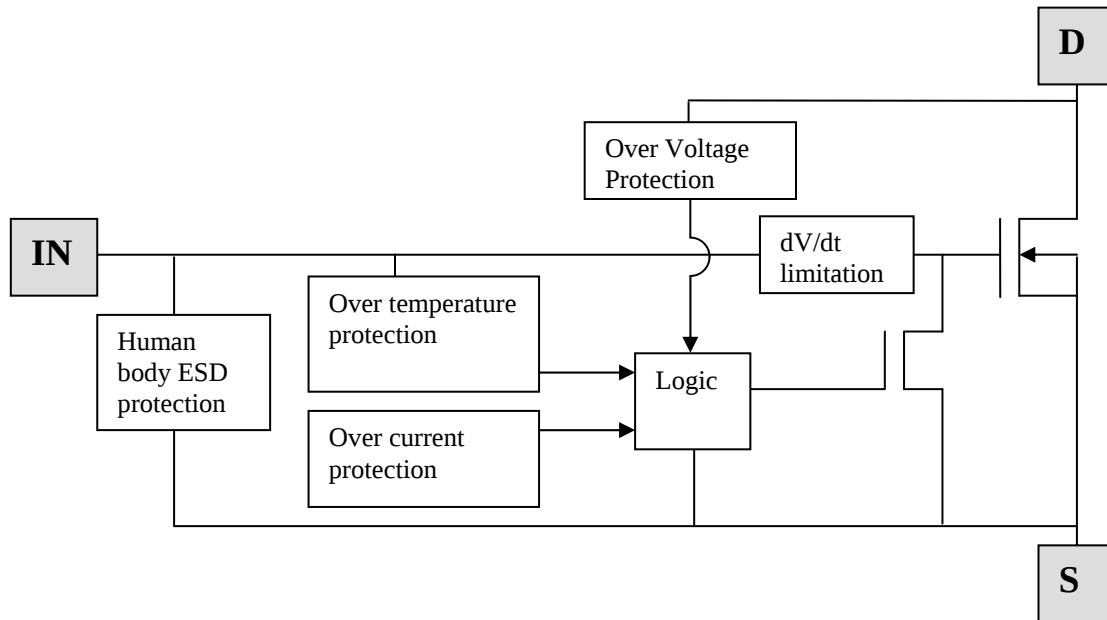

FEATURES

- Compact high power dissipation package
- Low input current
- Logic Level Input (3.3V and 5V)
- Short circuit protection with auto restart
- Over voltage protection (active clamp)
- Thermal shutdown with auto restart
- Over-current protection
- Input Protection (ESD)
- High continuous current rating

ORDERING INFORMATION

DEVICE	PART MARK	REEL SIZE (inches)	TAPE WIDTH (mm)	QUANTITY PER REEL
ZXMS6005SGTA	ZXMS 6005S	7	12 embossed	1,000 units

FUNCTIONAL BLOCK DIAGRAM



APPLICATIONS AND INFORMATION

- Especially suited for loads with a high in-rush current such as lamps and motors.
- All types of resistive, inductive and capacitive loads in switching applications.
- μC compatible power switch for 12V DC applications.
- Automotive rated.
- Replaces electromechanical relays and discrete circuits.
- Linear Mode capability - the current-limiting protection circuitry is designed to de-activate at low V_{DS} to minimise on state power dissipation. The maximum DC operating current is therefore determined by the thermal capability of the package/board combination, rather than by the protection circuitry. This does not compromise the product's ability to self-protect at low V_{DS} .

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	LIMIT	UNIT
Continuous Drain-Source Voltage	V_{DS}	60	V
Drain-Source Voltage for short circuit protection	$V_{DS(SC)}$	24	V
Continuous Input Voltage	V_{IN}	-0.5 ... +6	V
Continuous Input Current -0.2V ≤ V_{IN} ≤ 6V V_{IN} < -0.2V or V_{IN} > 6V	I_{IN}	No limit $ I_{IN} \leq 2$	mA
Operating Temperature Range	T_j	-40 to +150	°C
Storage Temperature Range	T_{stg}	-55 to +150	°C
Power Dissipation at $T_A = 25^\circ\text{C}$ (a)	P_D	1.0	W
Linear Derating Factor		8.0	mW/°C
Power Dissipation at $T_A = 25^\circ\text{C}$ (b)	P_D	1.6	W
Linear Derating Factor		12.8	mW/°C
Pulsed Drain Current @ $V_{IN} = 3.3\text{V}$	I_{DM}	5	A
Pulsed Drain Current @ $V_{IN} = 5\text{V}$	I_{DM}	6	A
Continuous Source Current (Body Diode) (a)	I_S	2.5	A
Pulsed Source Current (Body Diode)	I_{SM}	10	A
Unclamped single pulse inductive energy, $T_j = 25^\circ\text{C}$, $I_D = 0.5\text{A}$, $V_{DD} = 24\text{V}$	E_{AS}	480	mJ
Electrostatic Discharge (Human Body Model)	V_{ESD}	4000	V
Charged Device Model	V_{CDM}	1000	V

THERMAL RESISTANCE

PARAMETER	SYMBOL	VALUE	UNIT
Junction to Ambient (a)	$R_{\theta JA}$	125	°C/W
Junction to Ambient (b)	$R_{\theta JA}$	83	°C/W
Junction to Case (c)	$R_{\theta JC}$	39	°C/W

NOTES

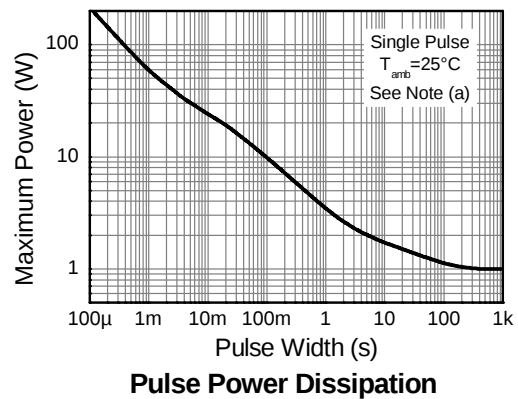
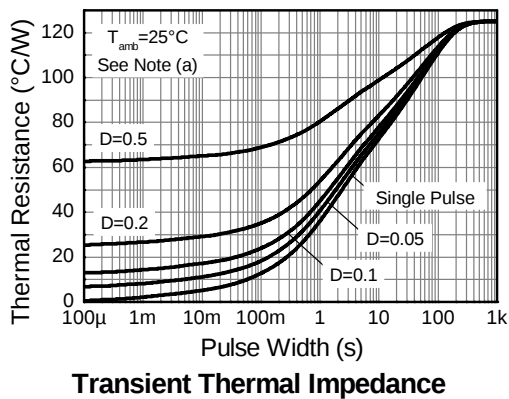
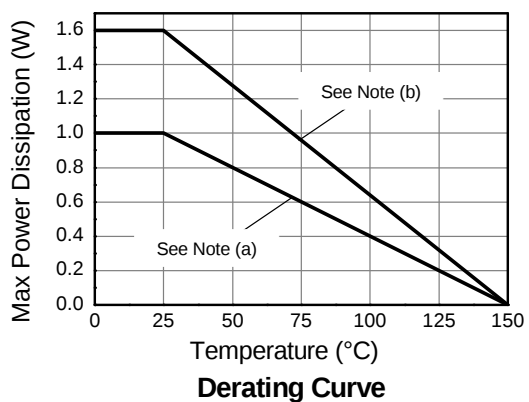
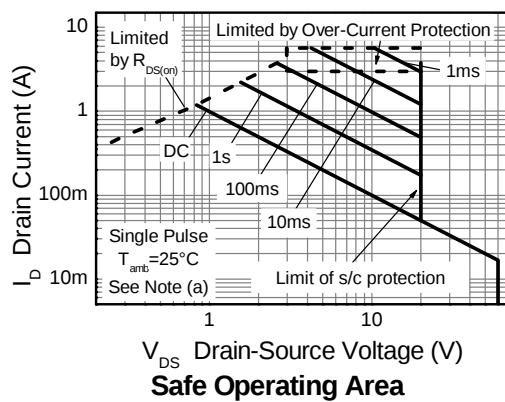
- For a device surface mounted on 15mm x 15mm single sided 1oz weight copper on 1.6mm FR4 board, in still air conditions. Sink split drain 80% and source 20% to isolate connections.
- For a device surface mounted on 50mm x 50mm single sided 2oz weight copper on 1.6mm FR4 board, in still air conditions. Sink split drain 80% and source 20% to isolate connections.
- Thermal resistance between junction and the mounting surfaces of drain and source pins.

RECOMMENDED OPERATING CONDITIONS

The ZXMS6005SG is optimised for use with μC operating from 3.3V and 5V supplies.

Symbol	Description	Min	Max	Units
V_{IN}	Input voltage range	0	5.5	V
T_{A}	Ambient temperature range	-40	125	$^{\circ}\text{C}$
V_{IH}	High level input voltage for MOSFET to be on	3	5.5	V
V_{IL}	Low level input voltage for MOSFET to be off	0	0.7	V
V_{P}	Peripheral supply voltage (voltage to which load is referred)	0	24	V

CHARACTERISTICS



ELECTRICAL CHARACTERISTICS (at $T_{amb} = 25^{\circ}\text{C}$ unless otherwise stated).

PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	CONDITIONS
Static Characteristics						
Drain-Source Clamp Voltage	$V_{DS(AZ)}$	60	65	70	V	$I_D=10\text{mA}$
Off state Drain Current	I_{DSS}			1	μA	$V_{DS}=12\text{V}, V_{IN}=0\text{V}$
Off state Drain Current	I_{DSS}			2	μA	$V_{DS}=36\text{V}, V_{IN}=0\text{V}$
Input Threshold Voltage	$V_{IN(th)}$	0.7	1	1.5	V	$V_{DS}=V_{GS}, I_D=1\text{mA}$
Input Current	I_{IN}		60	100	μA	$V_{IN}=+3\text{V}$
Input Current	I_{IN}		120	200	μA	$V_{IN}=+5\text{V}$
Input Current while over temperature active				300	μA	$V_{IN}=+5\text{V}$
Static Drain-Source On-State Resistance	$R_{DS(on)}$		170	250	$\text{m}\Omega$	$V_{IN}=+3\text{V}, I_D=1\text{A}$
Static Drain-Source On-State Resistance	$R_{DS(on)}$		150	200	$\text{m}\Omega$	$V_{IN}=+5\text{V}, I_D=1\text{A}$
Continuous Drain Current (a)	I_D	1.4			A	$V_{IN}=3\text{V}; T_A=25^{\circ}\text{C}$
Continuous Drain Current (a)	I_D	1.6			A	$V_{IN}=5\text{V}; T_A=25^{\circ}\text{C}$
Continuous Drain Current (b)	I_D	1.9			A	$V_{IN}=3\text{V}; T_A=25^{\circ}\text{C}$
Continuous Drain Current (b)	I_D	2.0			A	$V_{IN}=5\text{V}; T_A=25^{\circ}\text{C}$
Current Limit (d)	$I_{D(LIM)}$	2.2	5		A	$V_{IN}=+3\text{V},$
Current Limit (d)	$I_{D(LIM)}$	3.3	7		A	$V_{IN}=+5\text{V}$
Dynamic Characteristics						
Turn On Delay Time	$t_{d(on)}$		6		μs	$V_{DD}=12\text{V}, I_D=1\text{A}, V_{GS}=5\text{V}$
Rise time	t_r		14		μs	
Turn Off Delay Time	$t_{d(off)}$		34		μs	
Fall Time	t_f		19		μs	

Notes:

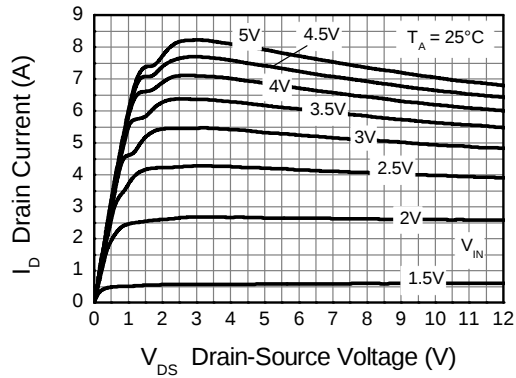
- (d) The drain current is restricted only when the device is in saturation (see graph 'typical output characteristic'). This allows the device to be used in the fully on state without interference from the current limit. The device is fully protected at all drain currents, as the low power dissipation generated outside saturation makes current limit unnecessary.

PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	CONDITIONS
Over-temperature Protection						
Thermal Overload Trip Temperature (e)	T _{JT}	150	175		°C	
Thermal hysteresis (e)			10		°C	

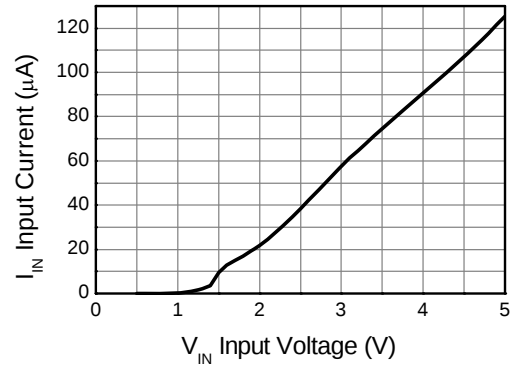
Note:

- (e) Over-temperature protection is designed to prevent device destruction under fault conditions. Fault conditions are considered as “outside” normal operating range, so this part is not designed to withstand over-temperature for extended periods..

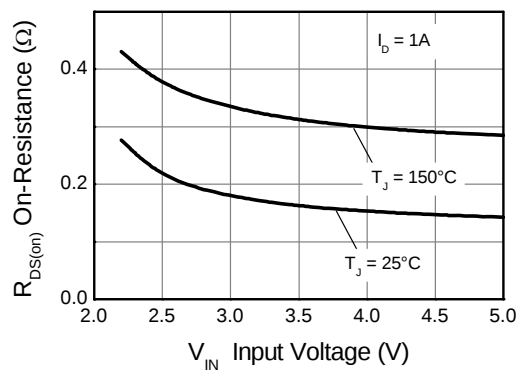
TYPICAL CHARACTERISTICS



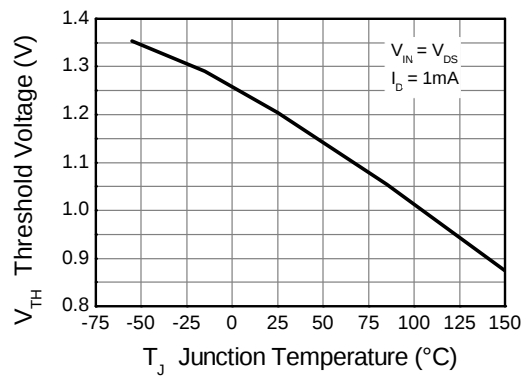
Typical Output Characteristic



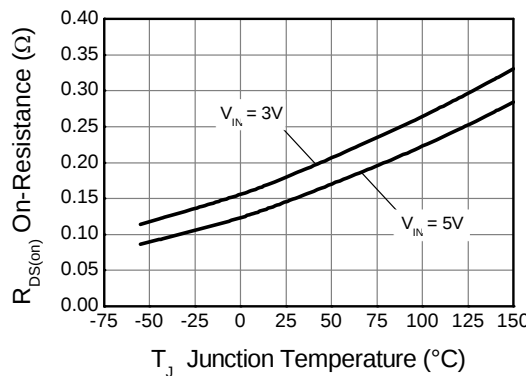
Input Current vs Input Voltage



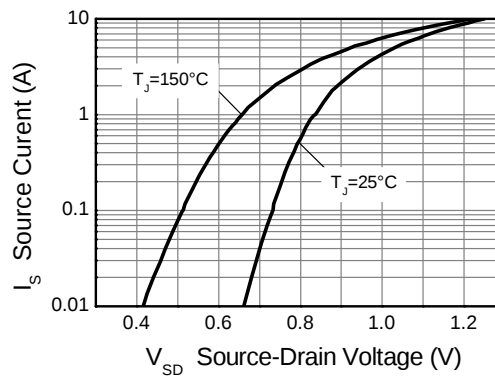
On-Resistance vs Input Voltage



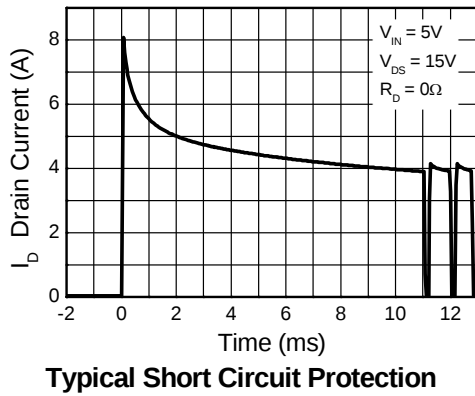
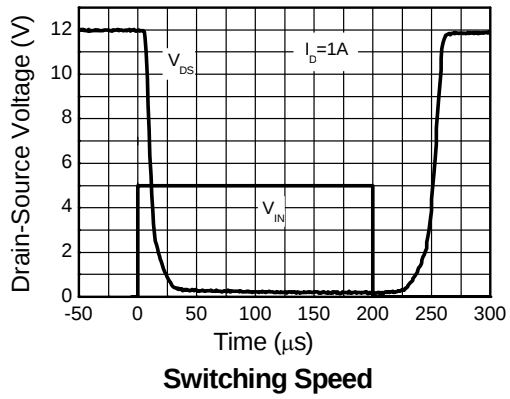
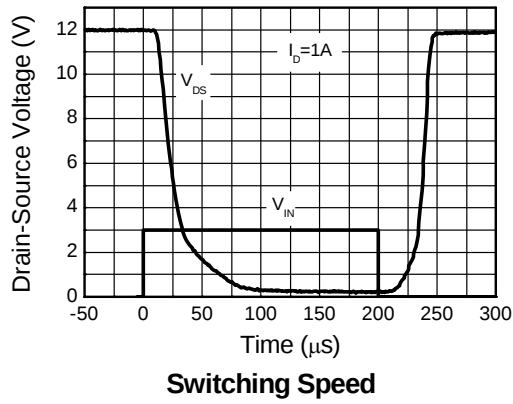
Threshold Voltage vs Temperature



On-Resistance vs Temperature



Reverse Diode Characteristic



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